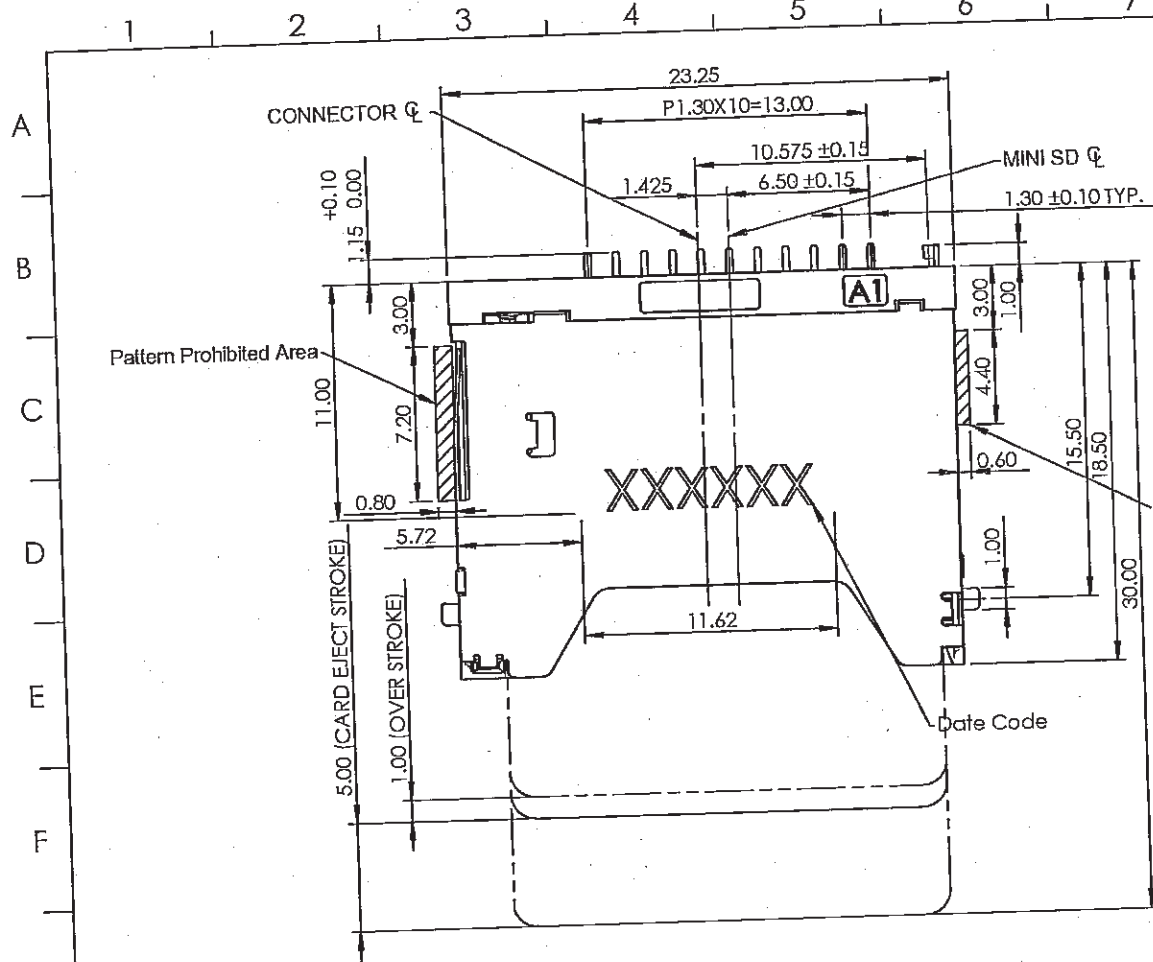
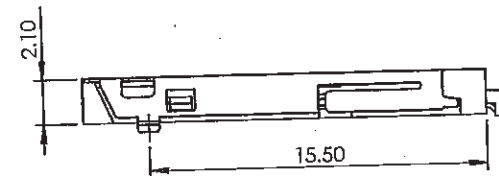
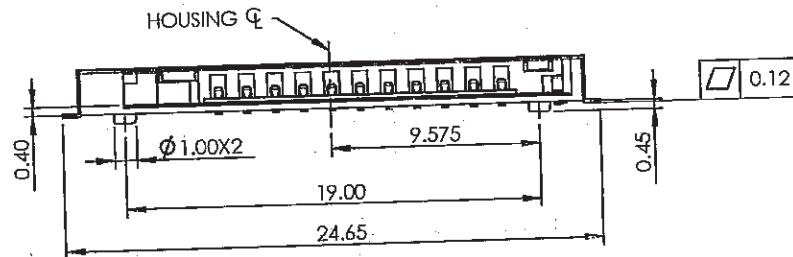


- NOTE:
- 1.MATERIAL:
HOUSING:HIGH TEMPERATURE THERMOPLASTIC,UL94V-0
TERMINAL:COPPER ALLOY.
COVER:STAINLESS STEEL.
 - 2.FINISH:
TERMINAL:
CONTACT AREA: Au OVER NI PLATE.
SOLDER TAIL: TIN/LEAD OR UNLEAD PLATING.
COVER: NI OVERALL.
PED: GOLD OVER NI PLATE.
 - 3.COPLANARITY MUST BE WITH IN 0.12
 - 4.PART NO. :
MIP011-X0-0X01
- 0-WITH DATE CODE/LOGO
1-WITHOUT DATE CODE/LOGO
2-WITH DATE CODE,WITHOUT LOGO
3-WITHOUT DATE CODE/WITH LOGO
- TIN/LEAD PLATING :
0-GOLD FLASH
2-10μ" GOLD
UNLEAD PLATING :
A-GOLD FLASH
C-10μ" GOLD



GENERAL TOLERANCE		Wellco T&C Co., Ltd.	
X ± 0.50	X° ± 5°	TITLE MINI SD-PUSH TYPE	
X ± 0.30	X° ± 2°		
XX ± 0.20	XX° ± 1°		
XXX ± 0.10	XXX° ± 0.5°	DWG NO. MIP011-02-B	
UNIT mm	PART NO. MIP011-X0-0X01	SCALE NONE	SHEET 1 / 2
APPROVAL <i>[Signature]</i>	CHECKED <i>[Signature]</i>	PROJ. <i>[Signature]</i>	REV. B

QP-04-04-B

